

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			New Release	05/22'20	Paul

ORDERING INFORMATION

SMPI - S07 (XX T)

① ② ③

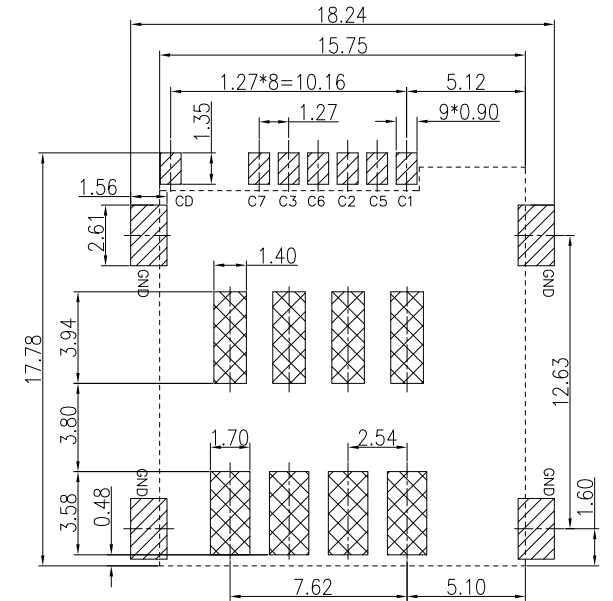
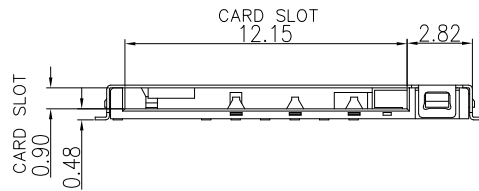
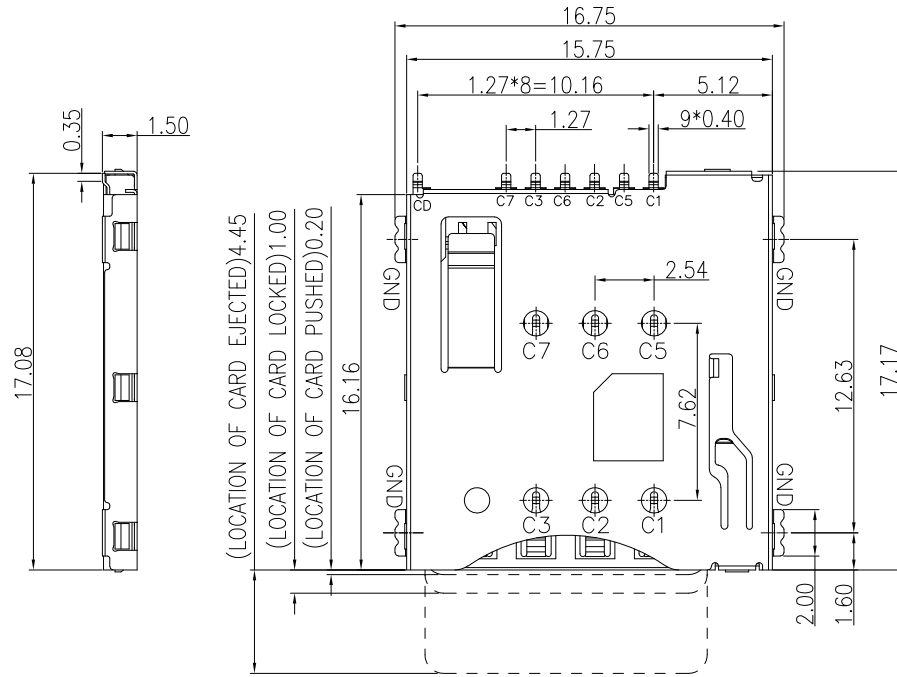
① **PRODUCT SERIES:**
Micro-SIM CARD SOCKET
PUSH-PUSH TYPE.

② **ITEM NO.:**
6+1PIN, 1.5mm Height.

CUSTOMER DRAWING

RoHS Compliant

③ **GOLD PLATING:**
01: G/F.



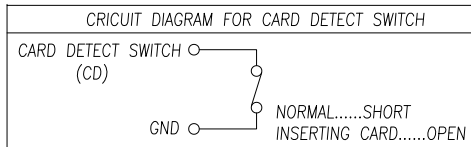
▨ PAD AREA
▩ KEEP OUT AREA

RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

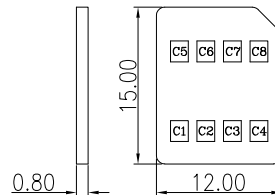
NOTES:

- MATERIAL:**
HOUSING: HIGH-TEMP, LCP, UL 94V-0.
CONTACT: COPPER ALLOY.
SHELL: STAINLESS STEEL.
- FINISH:**
CONTACT: GOLD OVER NICKEL ON CONTACT AREA.
SHELL: GOLD FLASH PLATED ON SOLDER TAILS.

MicroSIM CARD	
Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved



MicroSIM CARD



DIM	TOL
X.X	±0.30
X.XX	±0.20
X.XXX	±0.10

SUNFUN		SUNFUN TECHNOLOGY LTD			
DRAW NO.	SMPI-S07(A0)	DATE	MATERIAL: SEE NOTES	DRAW NAME:	
DESIGN:	Paul	05/22'20	FINISH: SEE NOTES	Micro-SIM Card Socket Push-Push Type, 6+1Pin 1.50mm Height	
CHECK:	Paul	05/22'20	FILE: SMPI-S07(A0)	MODEL: MICRO-SIM PP CONN	
REVIEW:	Sky	05/22'20	P/N: SMPI-S07(XXT)	UNIT: mm	SHEET: 1/1
APPROVED	Sky	05/22'20	REV. A0	SCALE	